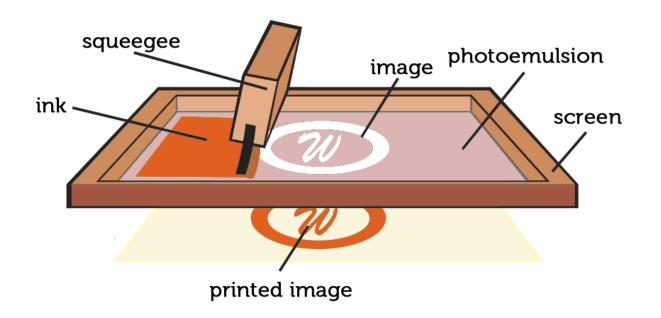
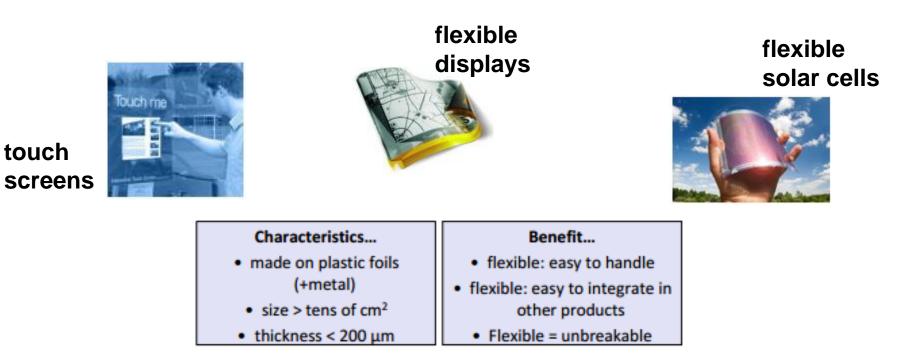
Screen Printing

Instrumental Technique Group Meeting (07-07-18)



- Ankit Nagar

Printing: Emerging Applications





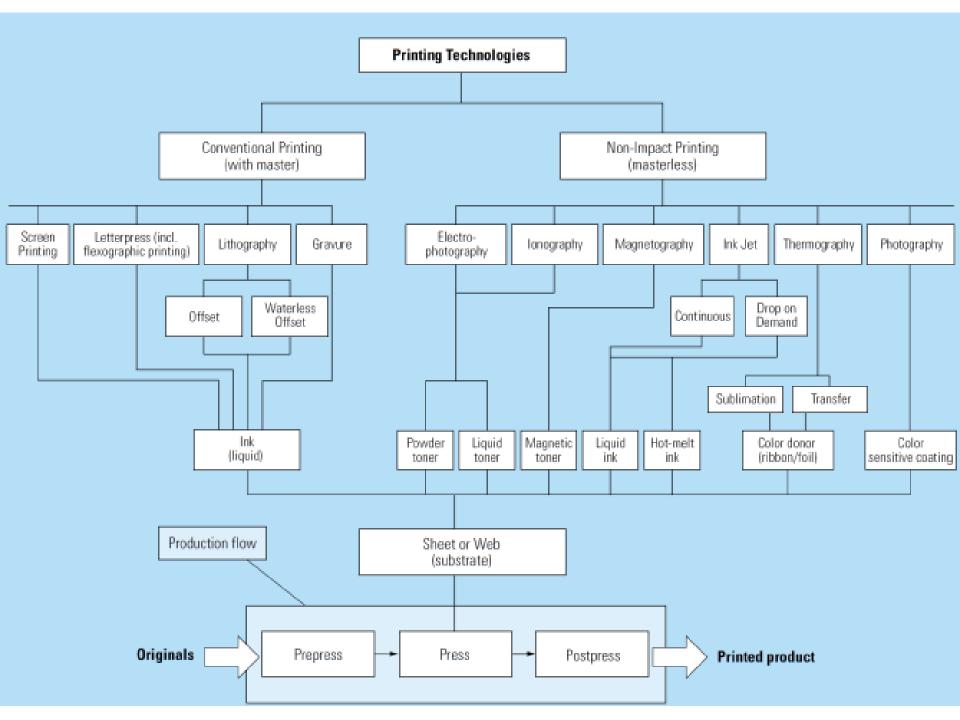
food and medicine monitoring sensors



health patches

flexible light emitting devices (OLEDs)





Plenty of Choices?

Limitations by available inks and substrates!

Surface Parameters

- Material
- Surface Energy
- Roughness
- Temperature performance
- Thickness
- Transparency

□ Processing Parameters

- Processing Temperature
- Shrinkage/ Deformation

Pretreatments necessary?

- R2R compatible
- Costs

Ink Parameters

- Surface Tension
- Concentration
- Solvent
- Viscosity/ Rheology

Ink Formulation

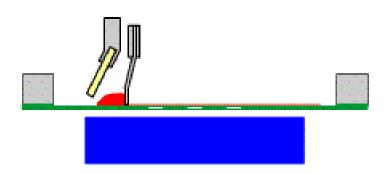
- Solubility
- Printability (Viscosity and surface tension)
- Environmental and safety issues

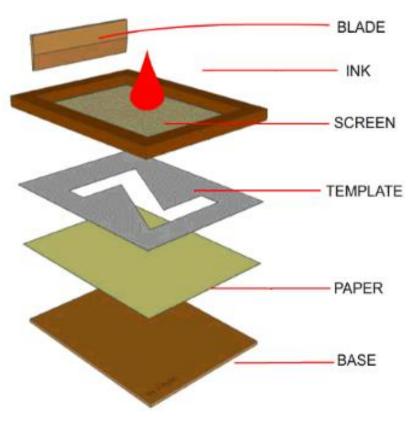
□ Layer Formation

- Ink and substrate interaction (wetting and spreading)
- Levelling -> Uniform layer
- Morphology

Screen Printing

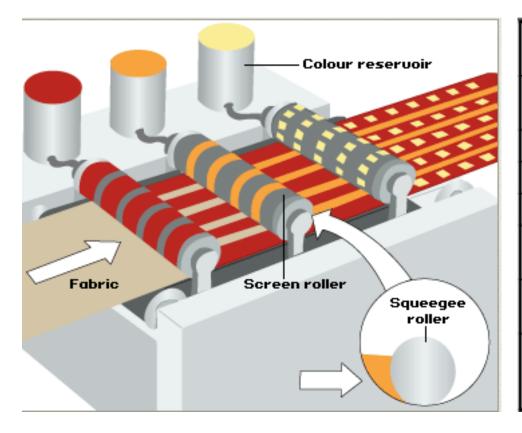
- Woven mesh supports ink blocking stencil
- Stencil forms open areas of mesh that transfer ink as image onto substrate
- Roller or squeegee is moved across the screen forcing ink past the threads of the woven mesh





https://hanguppictures.com/blog-post/understandingdifferent-print-runs-ap-pp-hc-type

Rotary Screen Printing



smallest feature size (lab)	20 µm	
smallest feature size (industrial scale)	80 µm	
ink viscosity range	100 – 80,000 mPas	
wet layer thickness	12 – 500 μm	
dry layer thickness	500 – 50,000 nm	
dry layer thickness accuracy	15 – 40 %	
alignment/overlay accuracy	100 μm	
linear line speed	>> 10 m/min, independent from resolution	

Key Features

- Silk/polymer/steel mesh with photo resist
- Inks: Oil-resin base, UV, solvent based, Water based, 10-400 Pa.s
- Short to medium runs posters, flyers, textiles, any rigid curved surface
- S2S speed 60 1500 sheets per hour.
- High definition screens: 500 mesh fabric, wire diameter 8 µm
- Challenges: material agglomeration, limits maximum particle size to $12 15 \,\mu\text{m}$

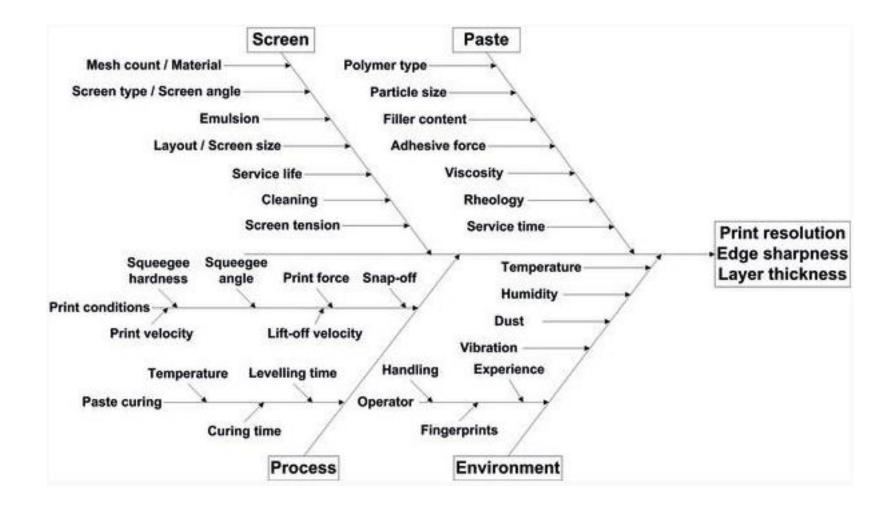
Solution Processing \rightarrow Ink

Ink parameters	Ink formulation	Company and
 Surface Tension Concentration Solvent Viscosity/ Rheology 	 Solubility Compatibility with active material Printability Environmental and safety issues Stability 	Solvent system 1 Poor homogeneity
Drying	Layer formation	Solvent system 2 Premature Precipitation
 Drying behavior and conditions Pre-drying step Hard baking Annealing 	 Ink and substrate interaction (wetting and spreading) Levelling -> uniform layer Pinning Morphology 	Solvent system 3 Most homogeneous coating

Devices

- Layer homogeneity
- Device performance and efficiency

Print Quality



https://epp-europe.industrie.de/technology/applications/process-for-highest-integration-density-on-wafer-level-dr-dr-andre-hanke-qimonda-dresden-gmbh-co-ohg-and-marco-luniak-dresden-university-of-technology-germany/#slider-intro-1

THANK YOU